

Product Change Notification - GBNG-05QUVX037

Date:

09 Aug 2018

Product Category:

8-bit Microcontrollers

Affected CPNs:

7

Notification subject:

CCB 3496 Initial Notice: Qualification of MMT as an additional assembly site for selected Atmel products of the 35.4K, 35.5K and 35.9K wafer technologies available in 100L TQFP (14x14x1.0mm) package.

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected Atmel products of the 35.4K, 35.5K and 35.9K wafer technologies available in 100L TQFP (14x14x1.0mm) package.

Pre Change:

Assembled in ASE using Au, PdCu or CuPdAu wire, CRM-1076WA die attach, G631H mold compound and C7025 lead frame material with MSL 3 classification or assembled in LPI using Au or CuPdAu wire and CRM-1033BF die attach material with MSL 3 classification.

Post Change:

Assembled in ASE using Au, PdCu or CuPdAu wire, CRM-1076WA die attach, G631H mold compound and C7025 lead frame material with MSL 3 classification or assembled in LPI using Au or CuPdAu wire and CRM-1033BF die attach material with MSL 3 classification.or assembled in MMT using Au wire, 3280 die attach, G700 mold compound and C194 lead frame material with MSL 1 or MSL 2 classification.

Pre and Post Change Summary:

		Pre	e Chan	ge		Post Change							
Assembly Site	ASE	SE Inc. Taiwan (ASE)		Lingsen Precision Industires, LTD. (LPI)		ASE Inc. Taiwar		n (ASE)	Lingsen Precision Industires, LTD. (LPI)		Microc hip Techno logy Thailan d (Branc h) (MMT)		
Wire material	Au	PdCu	CuPd Au	Au	CuPd Au	Au	PdCu	CuPdA u	Au	CuPdA u	Au		
Die attach material	CR	CRM-1076WA		CRM-1033BF		CRM-1076WA			CRM-1033BF		3280		



Molding						
compound	G631H	G700	G631H	G700	G700	
material						
Lead frame	C7025	C194	C7025	C194	C194	
material	07025	0134	07025	0134		
MSL					MSL 1	
Classificatio	MSL 3	MSL 3	MSL 3	MSL 3	or MSL	
n					2	

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To Improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

November 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2018					>	November 2018					
Workweek	31	32	33	34	35	>	44	45	46	47	48	
Initial PCN Issue Date		Х										
Qual Report Availability											Х	
Final PCN Issue Date											Х	

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

August 09, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_GBNG-05QUVX037_Qual_Plan.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATMEGA1280-16AU ATMEGA1280-16AU-HCM ATMEGA1280-16AUR ATMEGA1280V-8AU ATMEGA1280V-8AUR ATMEGA2560-16AUA0 ATMEGA2560-16AU-HCM ATMEGA2560-16AUR ATMEGA2560-16AURA0 ATMEGA2560V-8AU ATMEGA2560V-8AUA0 ATMEGA2560V-8AUR ATMEGA2560V-8AURA0 ATMEGA3250-16AU ATMEGA3250-16AUR ATMEGA3250A-AU ATMEGA3250A-AUR ATMEGA3250P-20AU ATMEGA3250P-20AUR ATMEGA3250PA-AU ATMEGA3250PA-AUR ATMEGA3250PV-10AU ATMEGA3250PV-10AUR ATMEGA3250V-8AU ATMEGA3250V-8AUR ATMEGA3290-16AU ATMEGA3290-16AUR ATMEGA3290A-AU ATMEGA3290A-AUR ATMEGA3290P-20AU ATMEGA3290P-20AUR ATMEGA3290PA-AU ATMEGA3290PA-AUR ATMEGA3290PV-10AU ATMEGA3290PV-10AUA0 ATMEGA3290PV-10AUR ATMEGA3290V-8AU ATMEGA3290V-8AUR ATMEGA640-16AU ATMEGA640-16AUR ATMEGA640-16AURA0 ATMEGA640V-8AU ATMEGA640V-8AUR ATMEGA6450-16AU ATMEGA6450-16AUR ATMEGA6450A-AU

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ATMEGA6450A-AUR ATMEGA6450P-AU ATMEGA6450P-AUR ATMEGA6450V-8AU ATMEGA6450V-8AUR ATMEGA6490-16AU ATMEGA6490-16AUR ATMEGA6490A-AU ATMEGA6490A-AUR ATMEGA6490P-AU ATMEGA6490P-AUR ATMEGA6490V-8AU ATMEGA6490V-8AUR ATXMEGA128A1-AU ATXMEGA128A1-AUR ATXMEGA128A1U-AN ATXMEGA128A1U-ANR ATXMEGA128A1U-AU ATXMEGA128A1U-AUR ATXMEGA128B1-ANR ATXMEGA128B1-AU ATXMEGA128B1-AUR ATXMEGA128B1-AURA0 ATXMEGA64A1-AU ATXMEGA64A1-AUR ATXMEGA64A1U-AU ATXMEGA64A1U-AUR ATXMEGA64B1-ANR ATXMEGA64B1-AU ATXMEGA64B1-AUA0 ATXMEGA64B1-AUR